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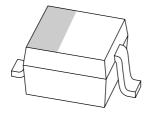
If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS

DATA SHEET



BAS321 General purpose diode

Product data sheet Supersedes data of 1999 Feb 09



General purpose diode

BAS321

FEATURES

- Small plastic SMD package
- Switching speed: max. 50 ns
- · General application
- Continuous reverse voltage: max. 200 V
- Repetitive peak reverse voltage: max. 250 V
- Repetitive peak forward current: max. 625 mA.

APPLICATIONS

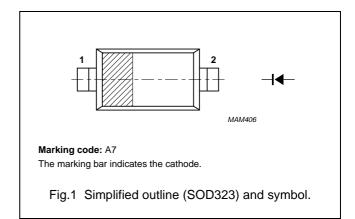
• General purpose switching in e.g. surface mounted circuits.

DESCRIPTION

The BAS321 is a general purpose diode fabricated in planar technology and encapsulated in a plastic SOD323 package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



ORDERING INFORMATION

TYPE		PACKAGE			
NUMBER	NAME	DESCRIPTION VERSION			
BAS321	_	plastic surface mounted package; 2 leads SOI			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{RRM}	repetitive peak reverse voltage		_	250	V
V _R	continuous reverse voltage		_	200	V
I _F	continuous forward current	see Fig.2; note 1	_	250	mA
I _{FRM}	repetitive peak forward current	$t_p < 0.5 \text{ ms}; \ \delta \le 0.25$	_	625	mA
I _{FSM}	non-repetitive peak forward current	square wave; T _j = 25 °C prior to surge; see Fig.4			
		t = 1 μs	_	9	Α
		t = 100 μs	_	3	Α
		t = 10 ms	_	1.7	Α
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	_	300	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C

Note

1. Device mounted on an FR4 printed circuit-board.

General purpose diode

BAS321

CHARACTERISTICS

 T_{i} = 25 $^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V _F	forward voltage	see Fig.3		
		I _F = 100 mA	1	V
		I _F = 200 mA	1.25	V
I _R	reverse current	see Fig.5		
		V _R = 200 V	100	nA
		V _R = 200 V; T _j = 150 °C	100	μΑ
C _d	diode capacitance	f = 1 MHz; V _R = 0; see Fig.6	2	pF
t _{rr}	reverse recovery time	when switched from I_F = 30 mA to I_R = 30 mA; R_L = 100 Ω ; measured at I_R = 3 mA; see Fig.8	50	ns

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-s)}	thermal resistance from junction to soldering point	T _s = 90°C; note 1	130	K/W
R _{th(j-a)}	thermal resistance from junction to ambient	note 2	366	K/W

Notes

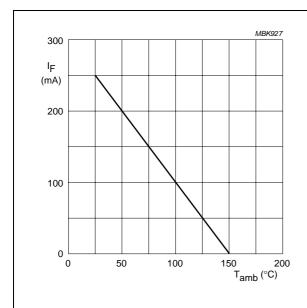
- 1. Soldering point of cathode tab.
- 2. Device mounted on an FR4 printed circuit board.

Product data sheet **NXP Semiconductors**

General purpose diode

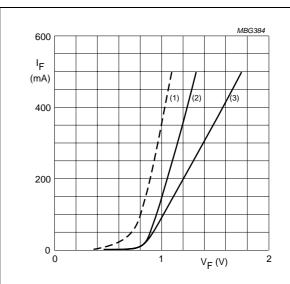
BAS321

GRAPHICAL DATA



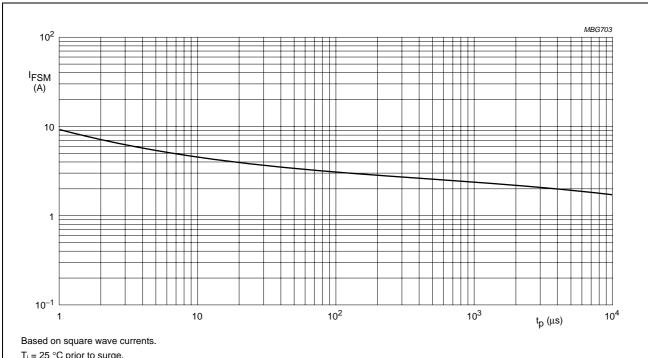
Device mounted on an FR4 printed-circuit board.

Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.



- (1) $T_i = 150 \,^{\circ}\text{C}$; typical values.
- (2) T_i = 25 °C; typical values.
- (3) T_i = 25 °C; maximum values.

Forward current as a function of Fig.3 forward voltage.



 $T_j = 25$ °C prior to surge.

Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.

General purpose diode

BAS321

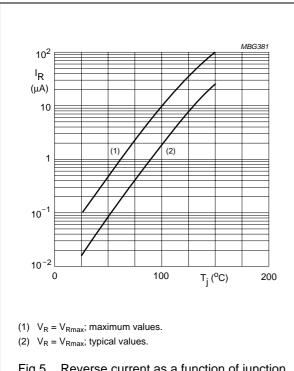
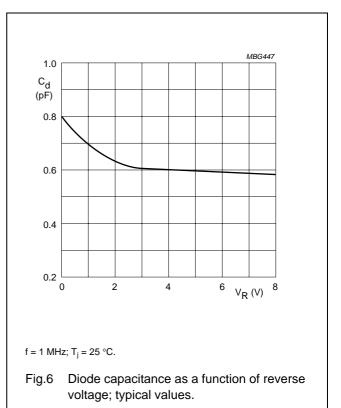
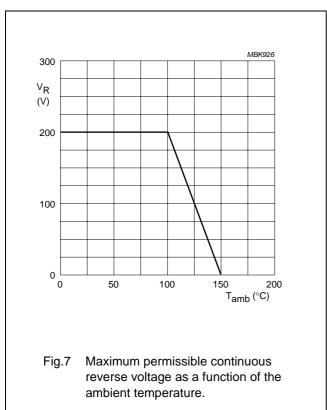


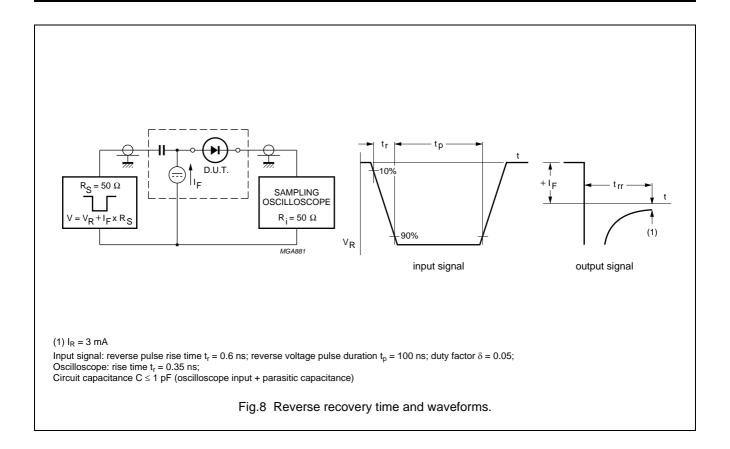
Fig.5 Reverse current as a function of junction temperature.





General purpose diode

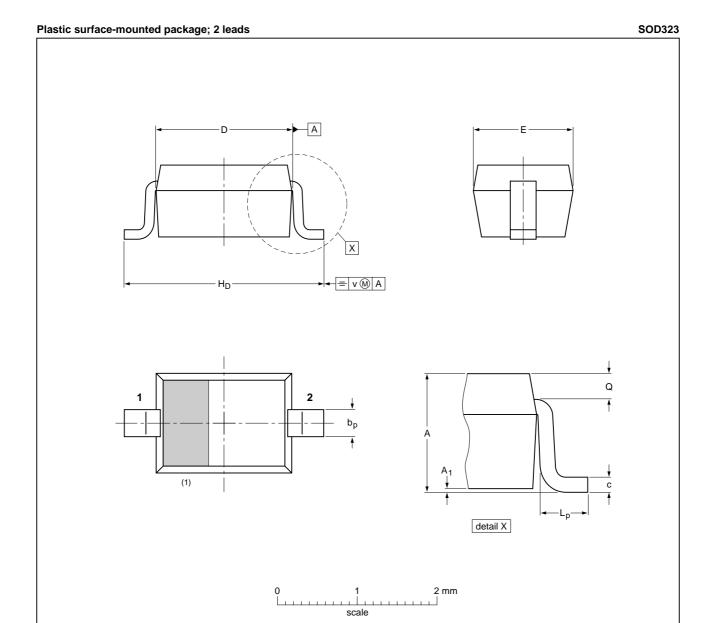
BAS321



General purpose diode

BAS321

PACKAGE OUTLINE



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	bp	С	D	E	H _D	Lp	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note
1. The marking bar indicates the cathode

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOD323			SC-76			03-12-17 06-03-16

General purpose diode

BAS321

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com
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